

Thermal Pads

Order code	Manufacturer code	Description
38-0400	625-54 (T0220) AC	PK10 FLEXIBLE HI-FLOW 625 T0220
38-0402	625-104 (T03P) AC	PK10 FLEXIBLE HI-FLOW 625 T03P

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The enclosed information is believed to be correct, Information may change 'without notice' due to product improvement. Users should ensure that the product is suitable for their use. E. & O. E.	Revision A 04/07/2003

Flexible Hi-Flow 625 Thermal Interface Material

Bergquist Hi-Flow 625

Bergquist Hi-Flow 625 is a film reinforced phase change material . The product consists of a thermally conductive 65°C phase change compound coated on an electrically insulating film. Hi-Flow 625 is designed to be used as a thermal interface material between electronic power devices that require electrical isolation and a heat sink. The film reinforcement makes Hi-Flow 625 easy to handle, and the 65°C phase change temperature of the coating material eliminates shipping and handling problems. Hi-Flow 625 has a continuous use temperature of 150°C.

<u>Physical Properties</u>	<u>Typical Value (mm)</u>		<u>Test Method</u>
Colour	Green		Visual
Thickness of Substrate	0.005 in	(0.13)	ASTM D 374
Tensile Strength	30 Kpsi	(210 Mpa)	ASTM D 882A
Elongation	60%		ASTM D 882A
Phase Change Temperature	65°C		DSC
Continuous Use Temperature	150°C		
<u>Thermal</u>			
Thermal Cond. Of Coating	0.8 W/m-K		ASTM D5470
Thermal Cond. Of Composite	0.4 W/m-K		ASTM D5470 ¹
Thermal Resistance (°C-in ² -W ⁻¹)	0.25 C-in ² /W	(1.6 C-cm ² /W)	ASTM D5470
<u>Electrical</u>			
Breakdown Voltage	4,000 Volt		ASTM D149
Dielectric Constant, 100Hz	3.5		ASTM D150
Volume Resistivity	>10 ¹⁰ ohm-m		ASTM D257
<u>Adhesive</u>			
Peel Strength	70 g/in	(28 g/cm)	ASTM D1876
Release Peel	25 g/in	(10 g/cm)	ASTM D1876

1. Sample run at 70°C